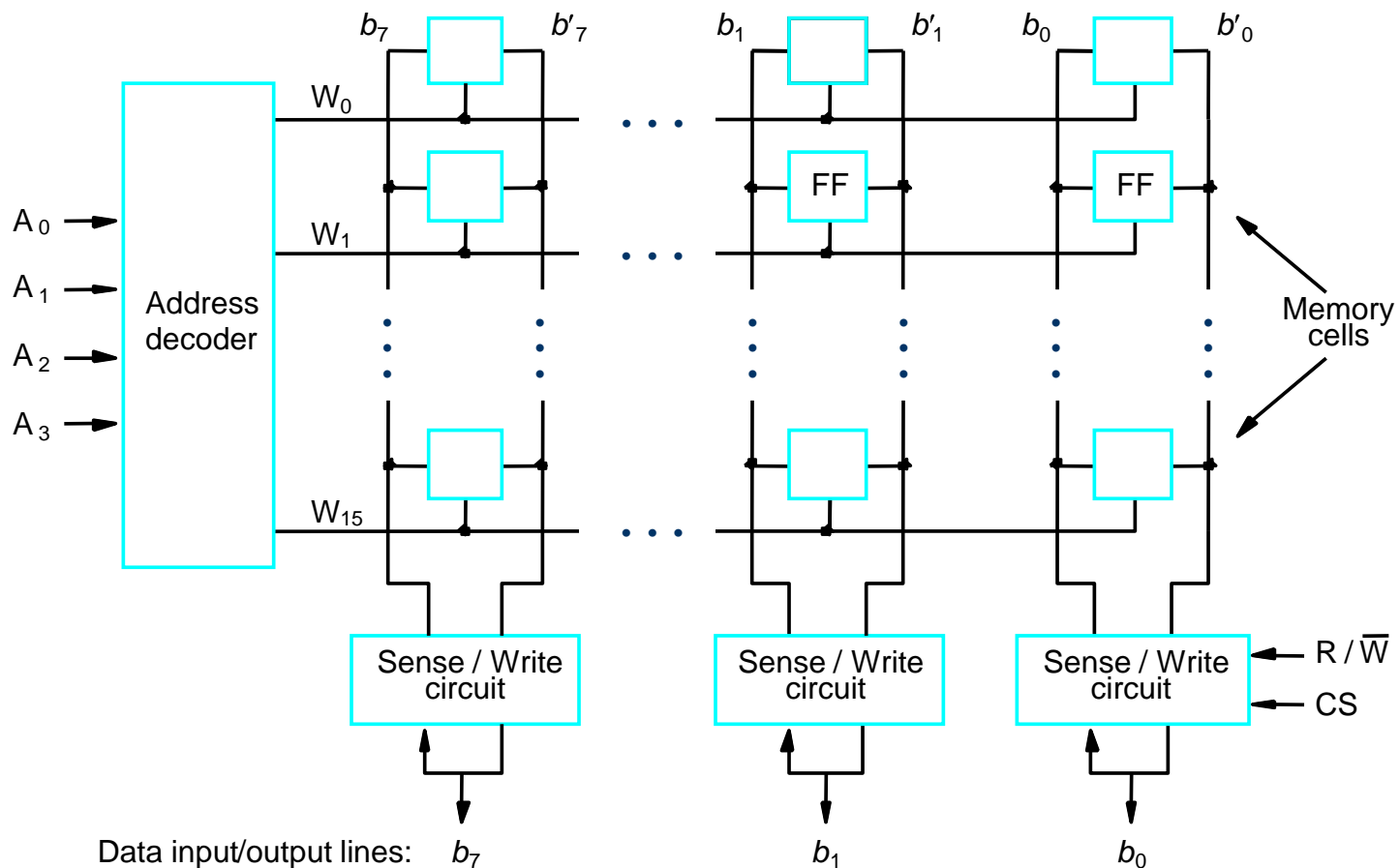


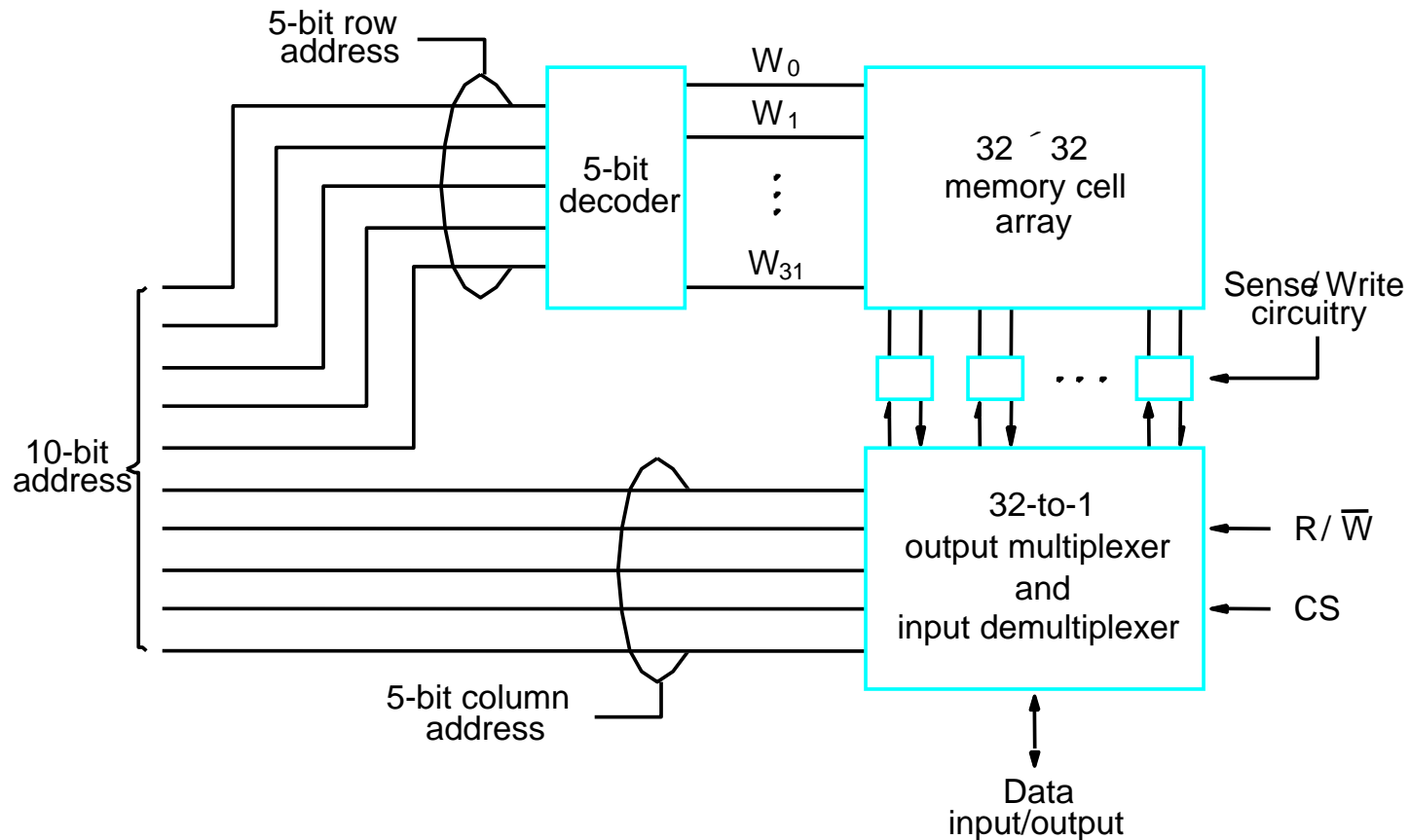


# Considerazioni Tecnologiche

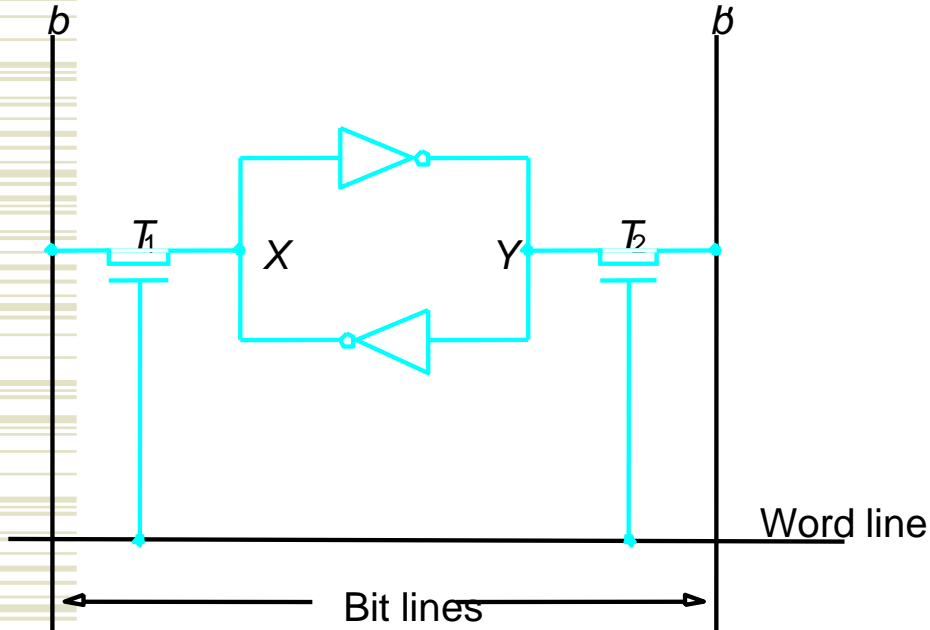
# Organizzazione di una RAM statica (16parole x 8bit)



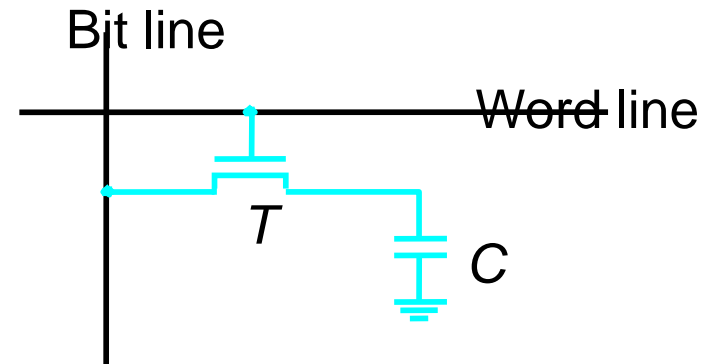
# Organizzazione di una memoria di $1K \times 1$



# Bit cell per memorie statiche e dinamiche (memorie volatili)

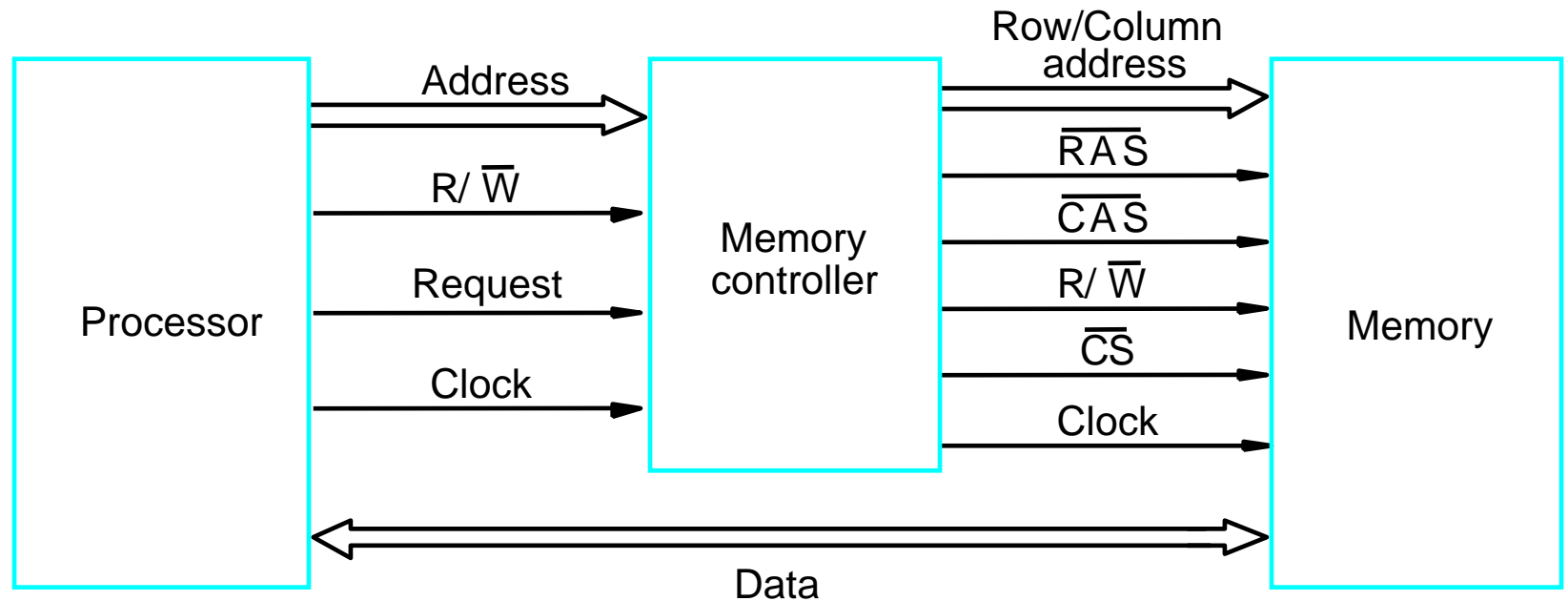


Cella di RAM statica (SRAM)

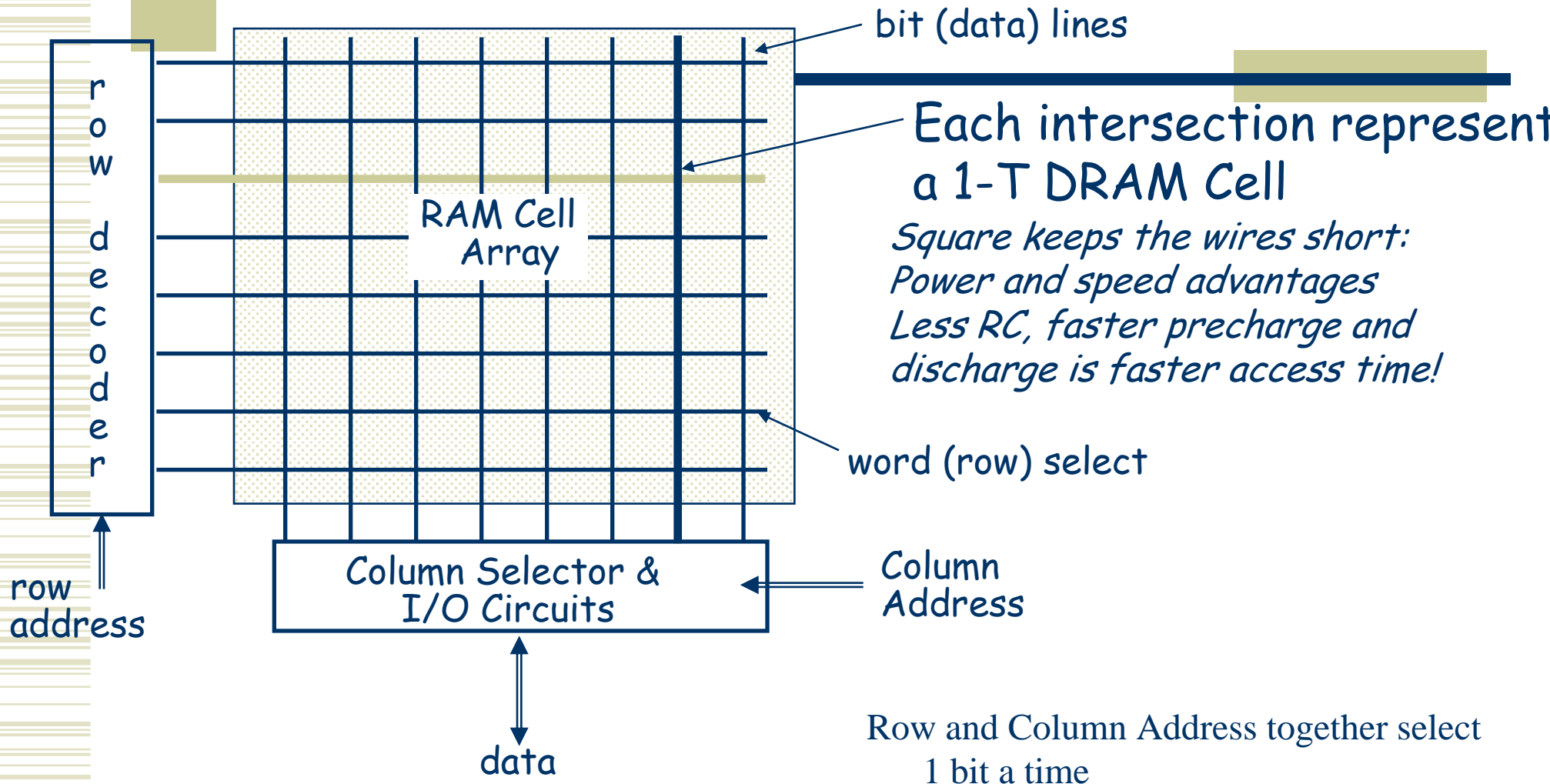


Cella di ram dinamica

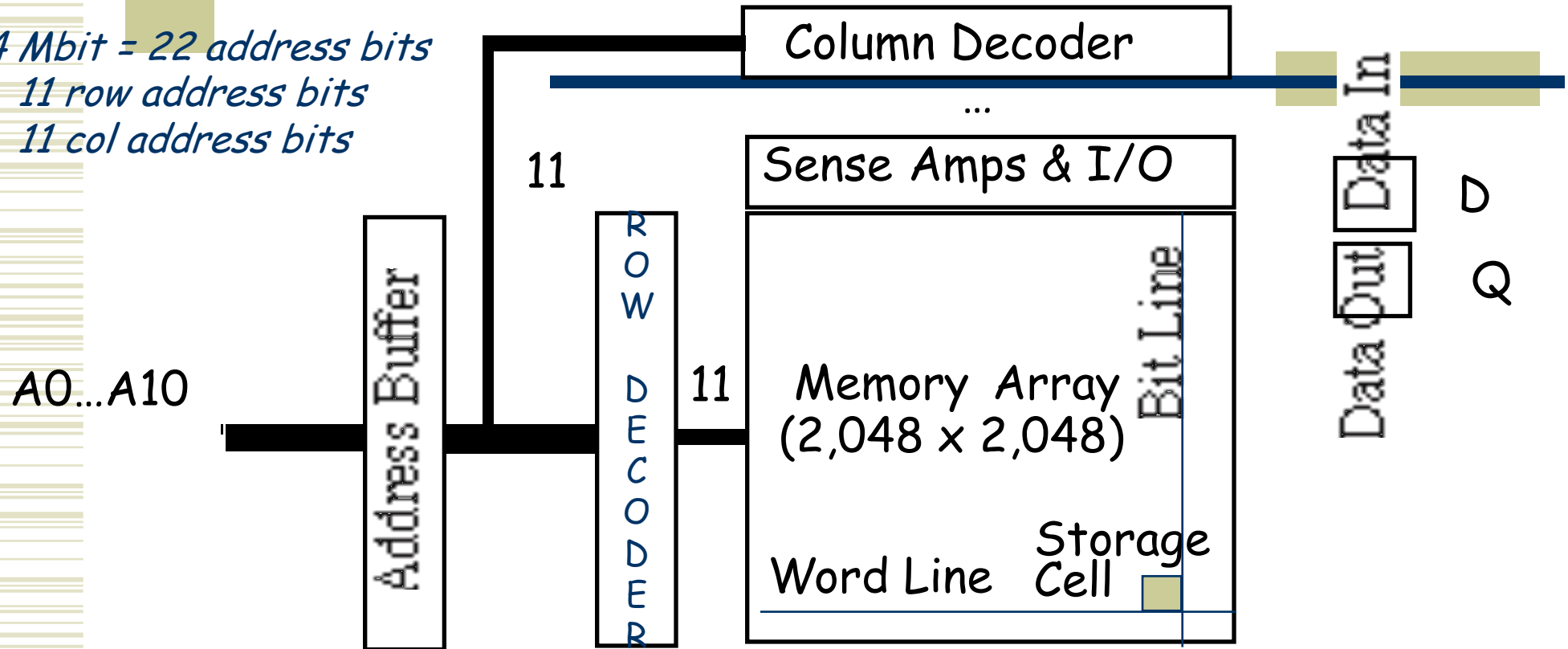
# Utilizzo del memory controller



# Classical DRAM Organization



# DRAM Logical Organization (4 Mbit)



- ◆ Square root of bits per RAS/CAS
  - Row selects 1 row of 2048 bits from 2048 rows
  - Col selects 1 bit out of 2048 bits in such a row

# Asynchronous DRAM: Organizzazione di una memoria dinamica da $2M \times 8$

Seleziono una riga e faccio il refresh

Row Address  
Strobe

$\overline{RAS}$

Row  
address  
latch

Row  
decoder

4096  $\times$  (512  $\times$  8)  
cell array

$A_{20-9} / A_{8-0}$

Column  
address  
latch

Sense / Write  
circuits

CS

$R/\overline{W}$

Column  
decoder

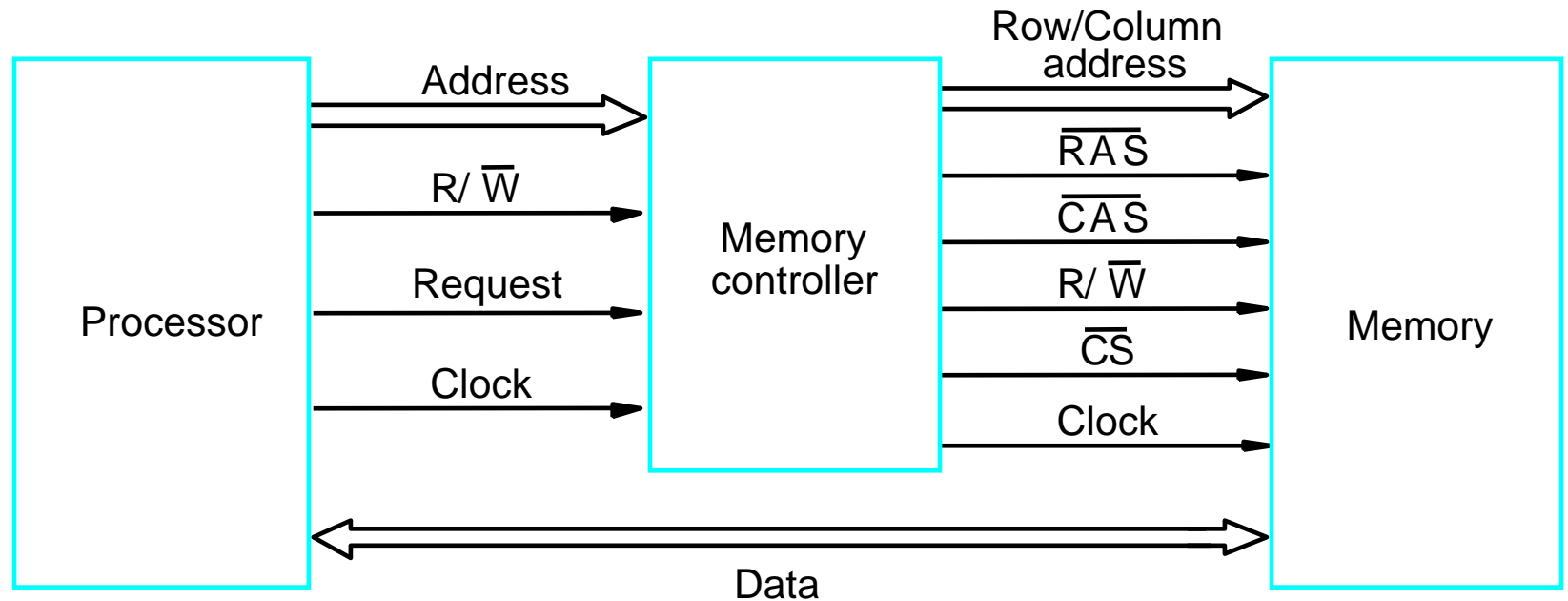
$D_7$   $D_0$

Column  
Address  
Strobe

$\overline{CAS}$



# Utilizzo del memory controller

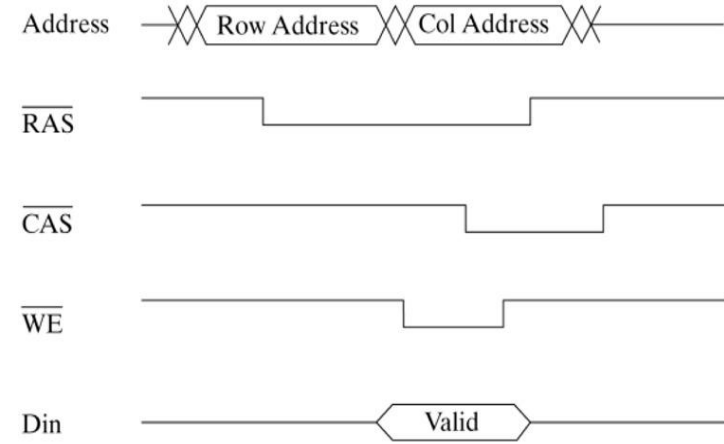
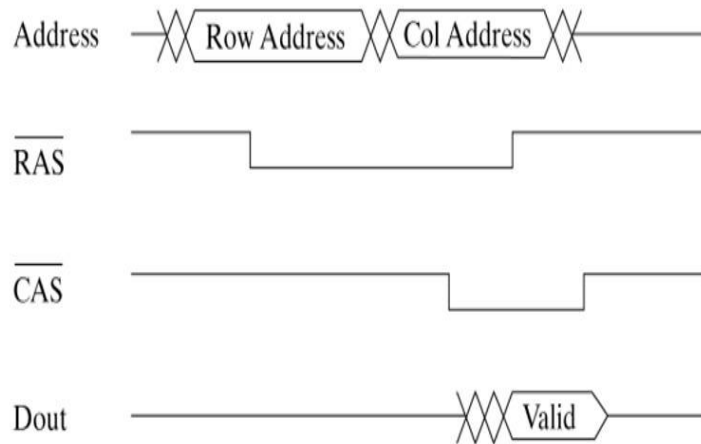


# Logic Diagram of a Typical DRAM



- ◆ Control Signals (RAS\_L, CAS\_L, WE\_L, OE\_L) are all active low
- ◆ Din and Dout are combined (D):
  - WE\_L is asserted (Low), OE\_L is disasserted (High)
    - D serves as the data input pin
  - WE\_L is disasserted (High), OE\_L is asserted (Low)
    - D is the data output pin
- ◆ Row and column addresses share the same pins (A)
  - RAS\_L goes low: Pins A are latched in as row address
  - CAS\_L goes low: Pins A are latched in as column address
  - RAS/CAS edge-sensitive

# Basic DRAM read & write

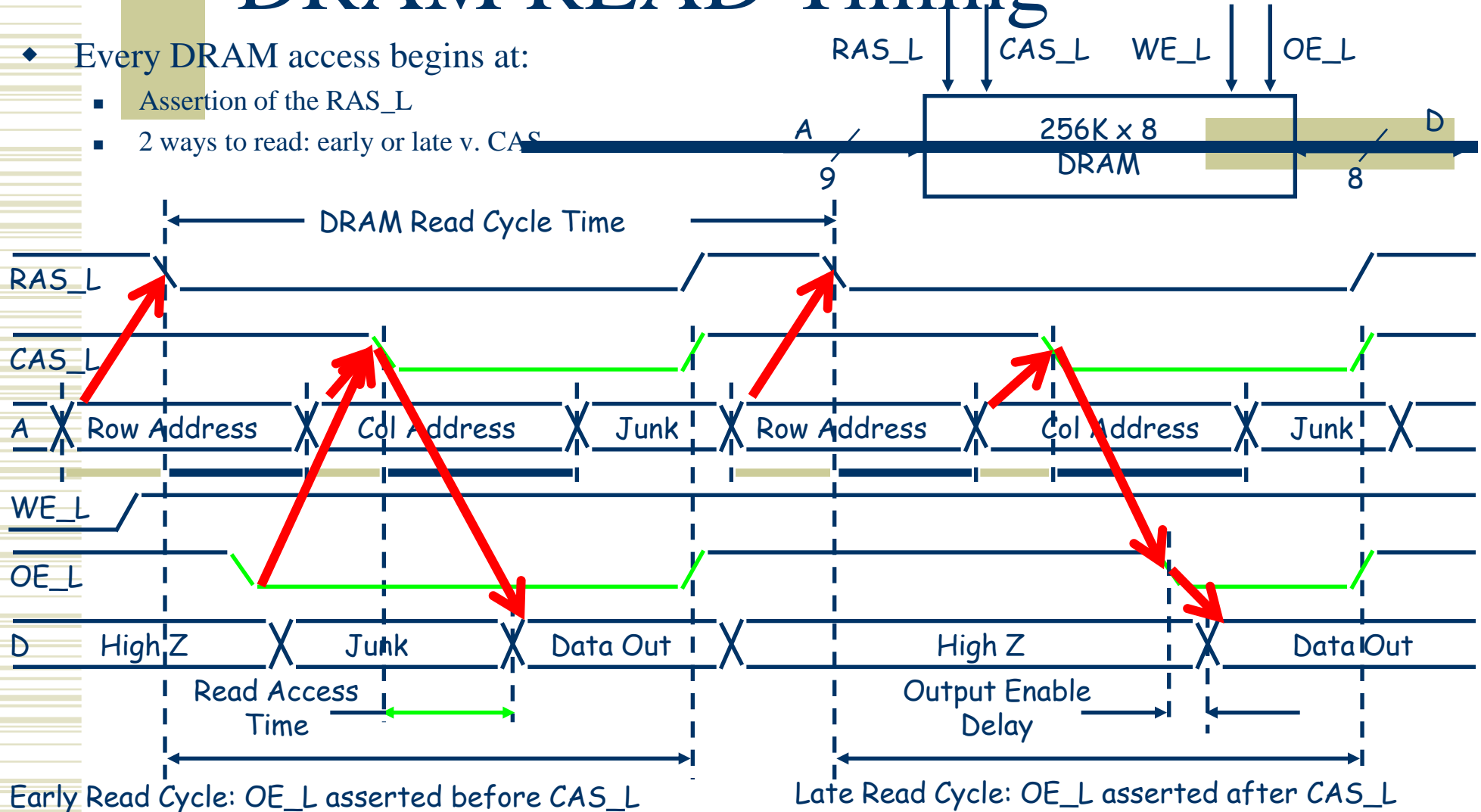


- ◆ Strobe address in two steps

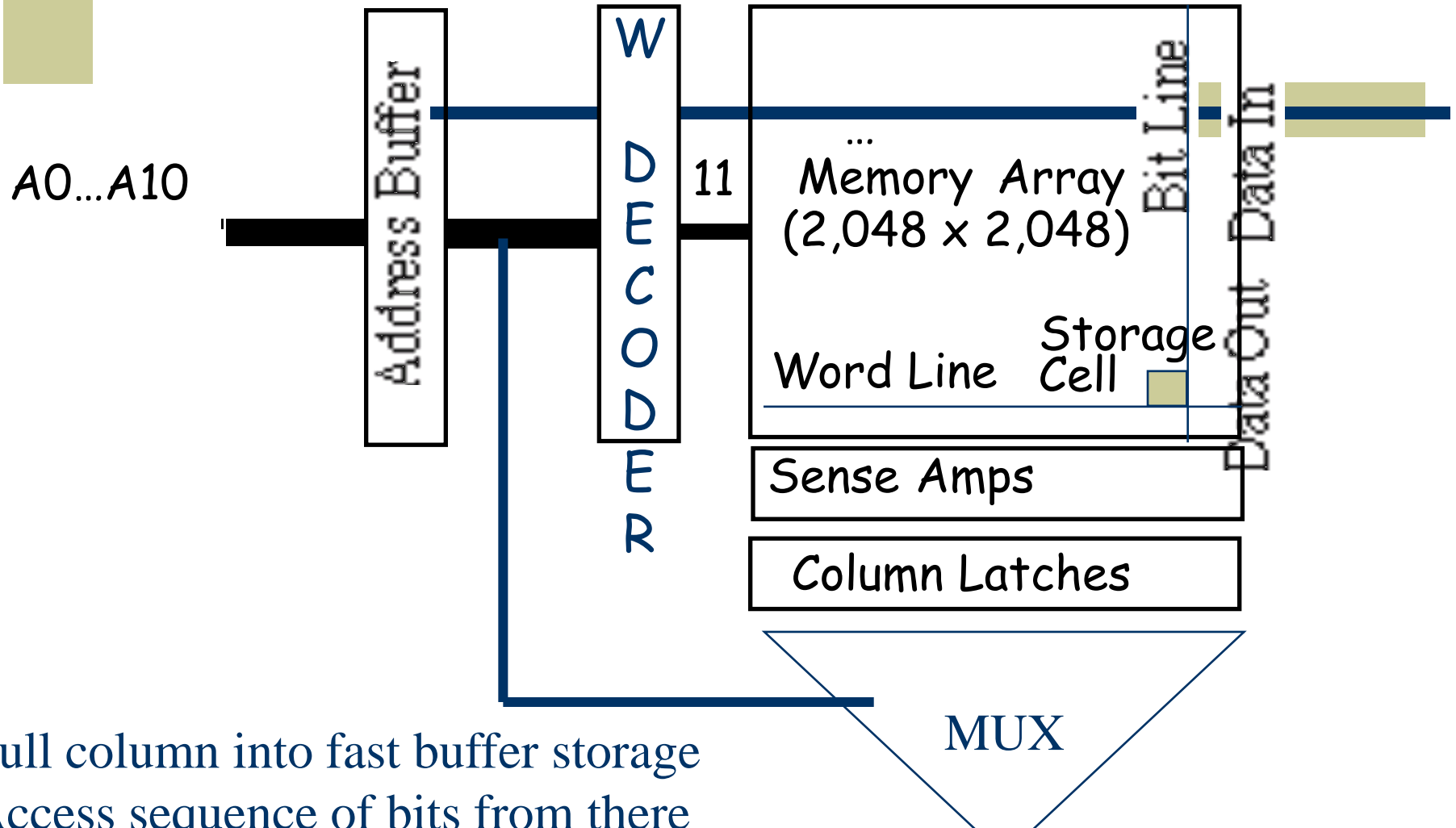
# DRAM READ Timing

- Every DRAM access begins at:

- Assertion of the RAS\_L
- 2 ways to read: early or late v. CAS



# DRAM with Column buffer



# Optimized Access to Cols in Row

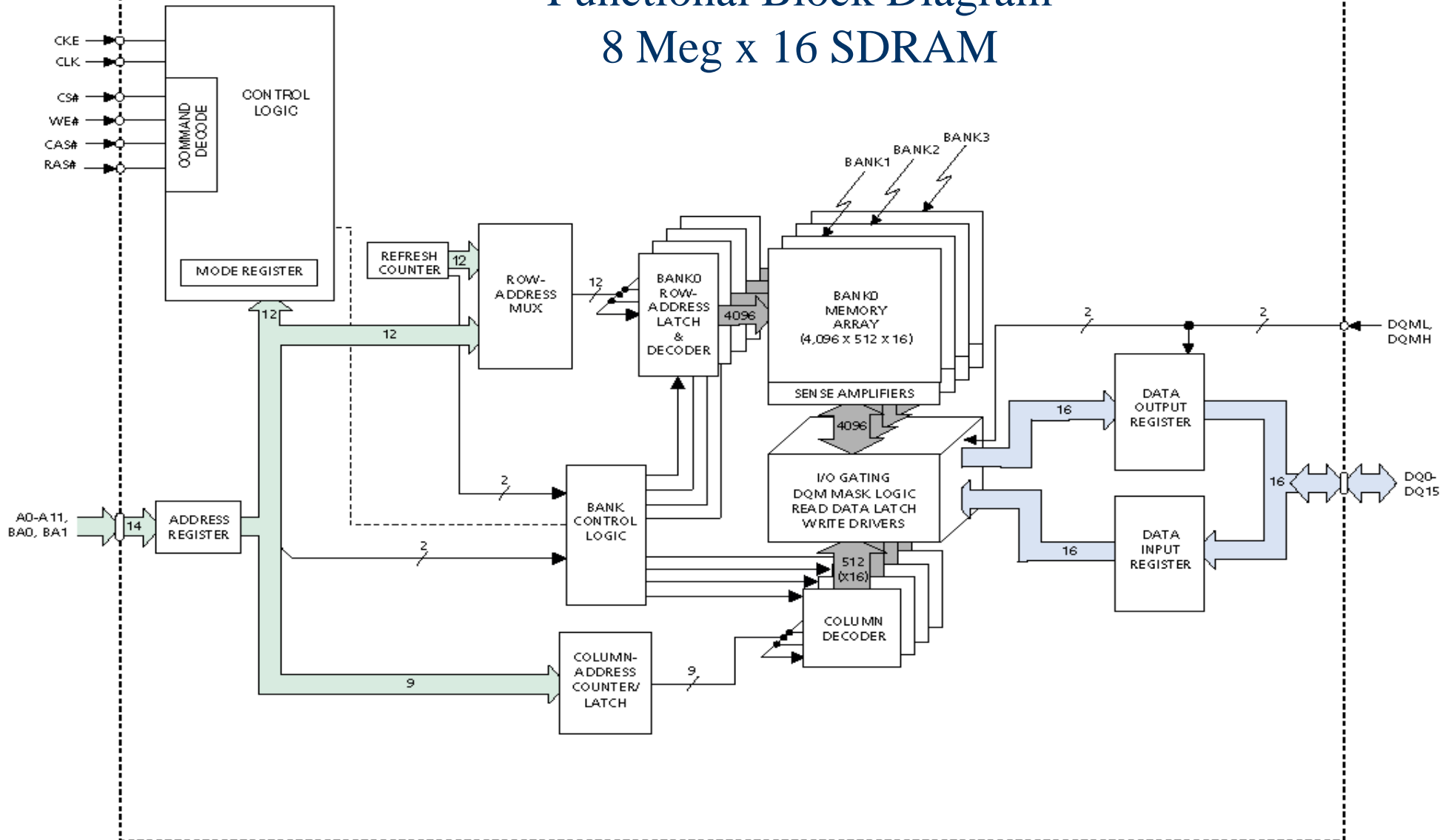
- ♦ Often want to access a sequence of bits
- ♦ Page mode
  - After RAS / CAS, can access additional bits in the row by changing column address and strobing CAS
- ♦ Static Column mode
  - Change column address (without repeated CAS) to get different bit
- ♦ Nibble mode
  - Pulsing CAS gives next bit mod 4
- ♦ Video ram
  - Serial access

# More recent DRAM enhancements

- ◆ EDO - extended data out (similar to fast-page mode)
  - RAS cycle fetched rows of data from cell array blocks (long access time, around 100ns)
  - Subsequent CAS cycles quickly access data from row buffers if within an address page (page is around 256 Bytes)
- ◆ SDRAM - synchronous DRAM
  - clocked interface
  - uses dual banks internally. Start access in one bank then next, then receive data from first then second.
- ◆ DDR - Double data rate SDRAM
  - Uses both rising (positive edge) and falling (negative) edge of clock for data transfer. (typical 100MHz clock with 200 MHz transfer).
- ◆ RDRAM - Rambus DRAM
  - Entire data blocks are access and transferred out on a high-speed bus-like interface (500 MB/s, 1.6 GB/s)
  - Tricky system level design. More expensive memory chips.

# Functional Block Diagram

## 8 Meg x 16 SDRAM

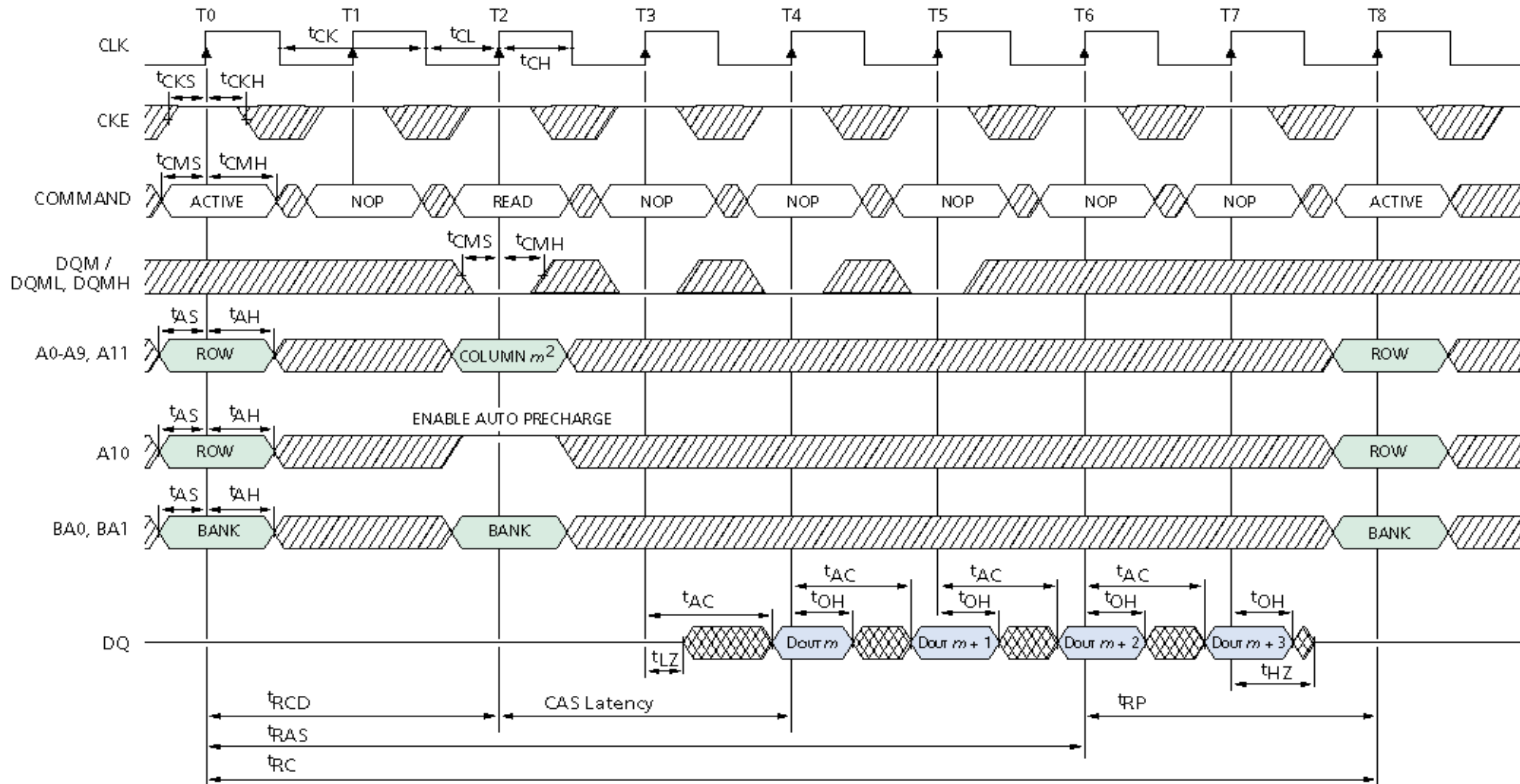




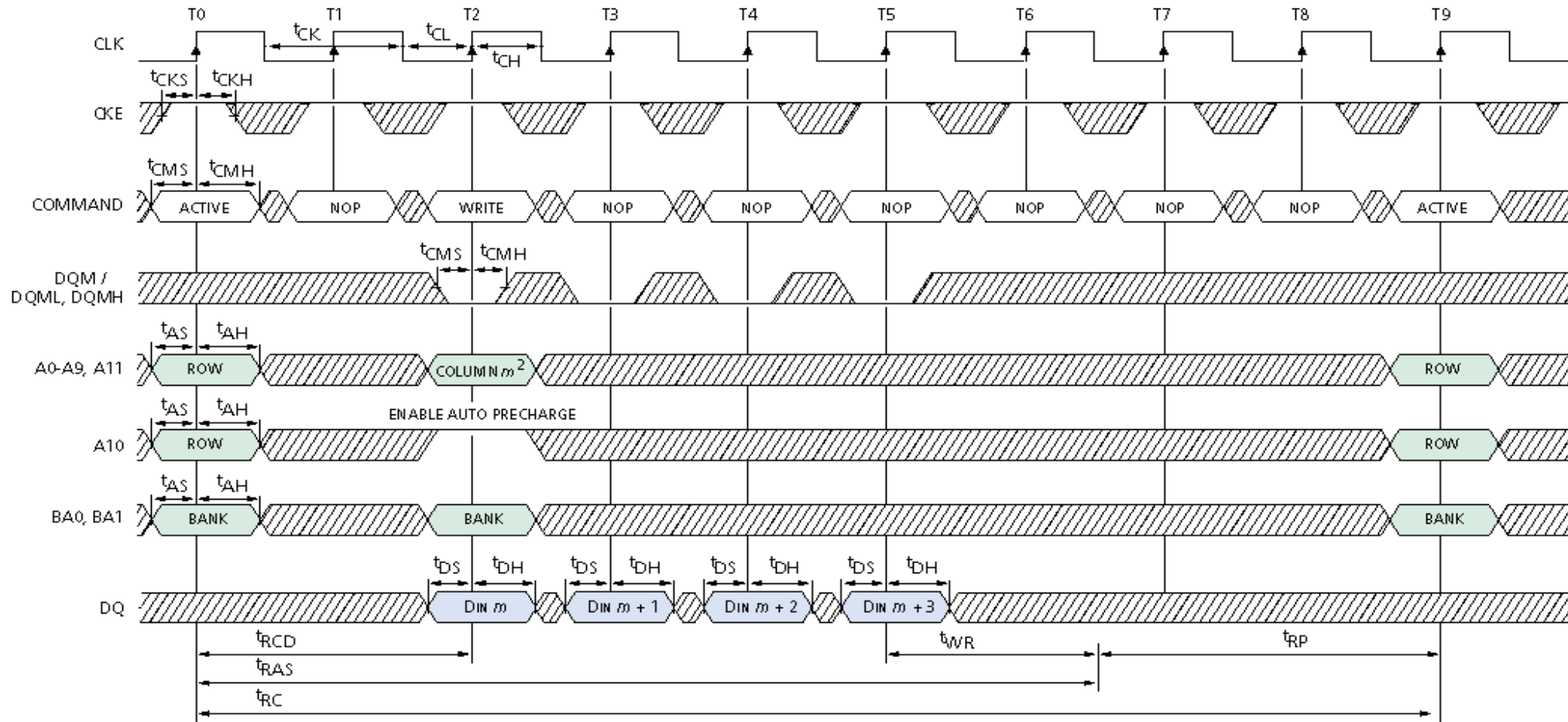
# SDRAM Details

- ◆ Multiple “banks” of cell arrays are used to reduce access time:
  - Each bank is 4K rows by 512 “columns” by 16 bits (for our part)
- ◆ Read and Write operations are split into RAS (row access) followed by CAS (column access)
- ◆ These operations are controlled by sending commands
  - Commands are sent using the RAS, CAS, CS, & WE pins.
- ◆ Address pins are “time multiplexed”
  - During RAS operation, address lines select the bank and row
  - During CAS operation, address lines select the column.
- ◆ “ACTIVE” command “opens” a row for operation
  - transfers the contents of the entire row to a row buffer
- ◆ Subsequent “READ” or “WRITE” commands modify the contents of the row buffer.
- ◆ For burst reads and writes during “READ” or “WRITE” the starting address of the block is supplied.
  - Burst length is programmable as 1, 2, 4, 8 or a “full page” (entire row) with a burst terminate option.
- ◆ Special commands are used for initialization (burst options etc.)
- ◆ A burst operation takes  $\approx 4 + n$  cycles (for  $n$  words)

# READ burst (with auto precharge)



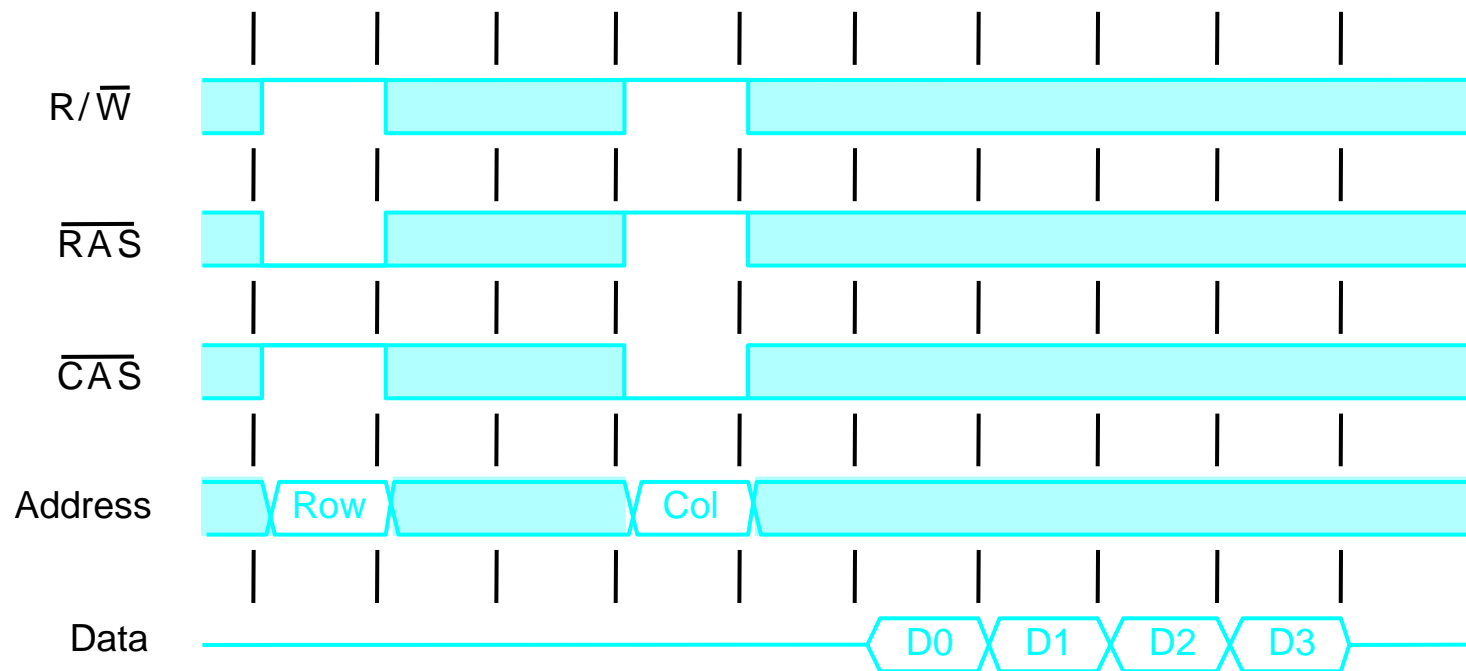
# WRITE burst (with auto precharge)



# Considerazioni sulla organizzazione ad array

- ◆ Locazioni di memoria consecutive si trovano sulla stessa linea;
- ◆ Se devo prelevare 2 o più byte consecutivi basta decodificare una sola volta l'indirizzo di riga e poi caricare gli indirizzi di colonna nei cicli successivi;
- ◆ Conclusione: il trasferimento di byte consecutivi avviene a frequenza doppia rispetto al trasferimento di 2 byte ad indirizzi casuali (aspetto importante nella progettazione delle cache)

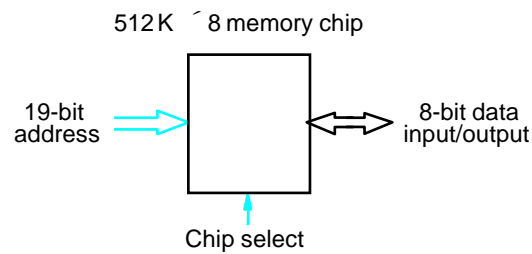
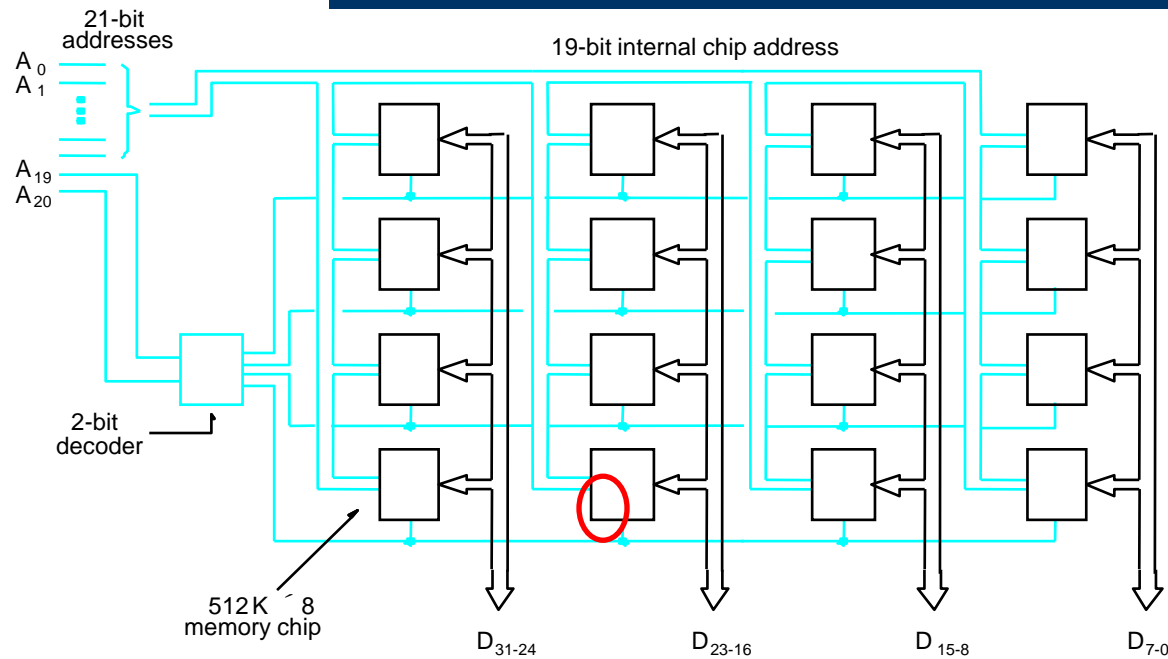
## Burst read of length 4



# RAM statiche Vs. RAM dinamiche

- ◆ Le RAM statiche sono molto veloci ma hanno costo e dimensioni elevate → vengono usate per la memoria cache (piccole e veloci)
- ◆ Le RAM dinamiche non sono molto veloci ed hanno bisogno di un circuito di refresh però occupano uno spazio molto limitato, sono adatte per memorie più grandi → vengono usate per la memoria principale del calcolatore (più lenta ma molto grande).

# Progetto di sottosistemi di memoria: Organization of a $2M \times 32$ memory module using 16 modules $512K \times 8$ static memory chips



# Riferimenti

- ◆ K. Hamacher, Computer Organization
  - Cap 5: The memory system
- ◆ Hennessy & Patterson: Computer Architecture, a quantitative approach (3<sup>rd</sup> Edition)
  - Cap 5